CLAIMS

1. A coin-type contactless information medium, comprising:

a substrate provided with an IC chip;

a metal ring including at least one slit portion; and

a protective member covering the substrate and the metal ring,

wherein the IC chip is located in a gap of the slit portion,

wherein the metal ring includes a step portion inside, and

wherein a peripheral edge portion of the substrate is in contact with the step portion.

2. The coin-type contactless information medium according to claim 1,

wherein the substrate comprises a protruding portion that fits into the at least one slit portion, and

wherein the IC chip is provided on the protruding portion.

3. The coin-type contactless information medium according to claim 1 or 2, wherein an upper surface of the IC chip is located lower than an upper surface of the metal ring in a side view.

4. The coin-type contactless information medium according to any one of claims 1 to 3, wherein the substrate is further provided with an antenna and an inductor connected in series to the antenna.

5. The coin-type contactless information medium according to claim 4, wherein the inductor is a chip inductor mounted on the substrate.

6. A method for manufacturing a coin-type contactless information medium, comprising the steps of:

mounting an IC chip on a protruding portion of a substrate;

fitting the protruding portion of the substrate into at least one slit portion included in a metal ring;

arranging the substrate on the metal ring so that a peripheral edge portion of the substrate is engaged with a step portion on an inside of the metal ring; and

forming a protective member covering the substrate and the metal ring using injection molding.

7. The method for manufacturing a coin-type contactless information medium according to claim 6, wherein the substrate is arranged on the metal ring so that an upper surface of the IC chip is located lower than an upper surface of the metal ring in a side view.

8. The method for manufacturing a coin-type contactless information medium according to claim 6 or 7, further comprising the step of mounting an inductor so as to be connected in series to the antenna formed on the substrate.

9. The method for manufacturing a coin-type contactless information medium according to claim 8, wherein the inductor is a chip inductor.